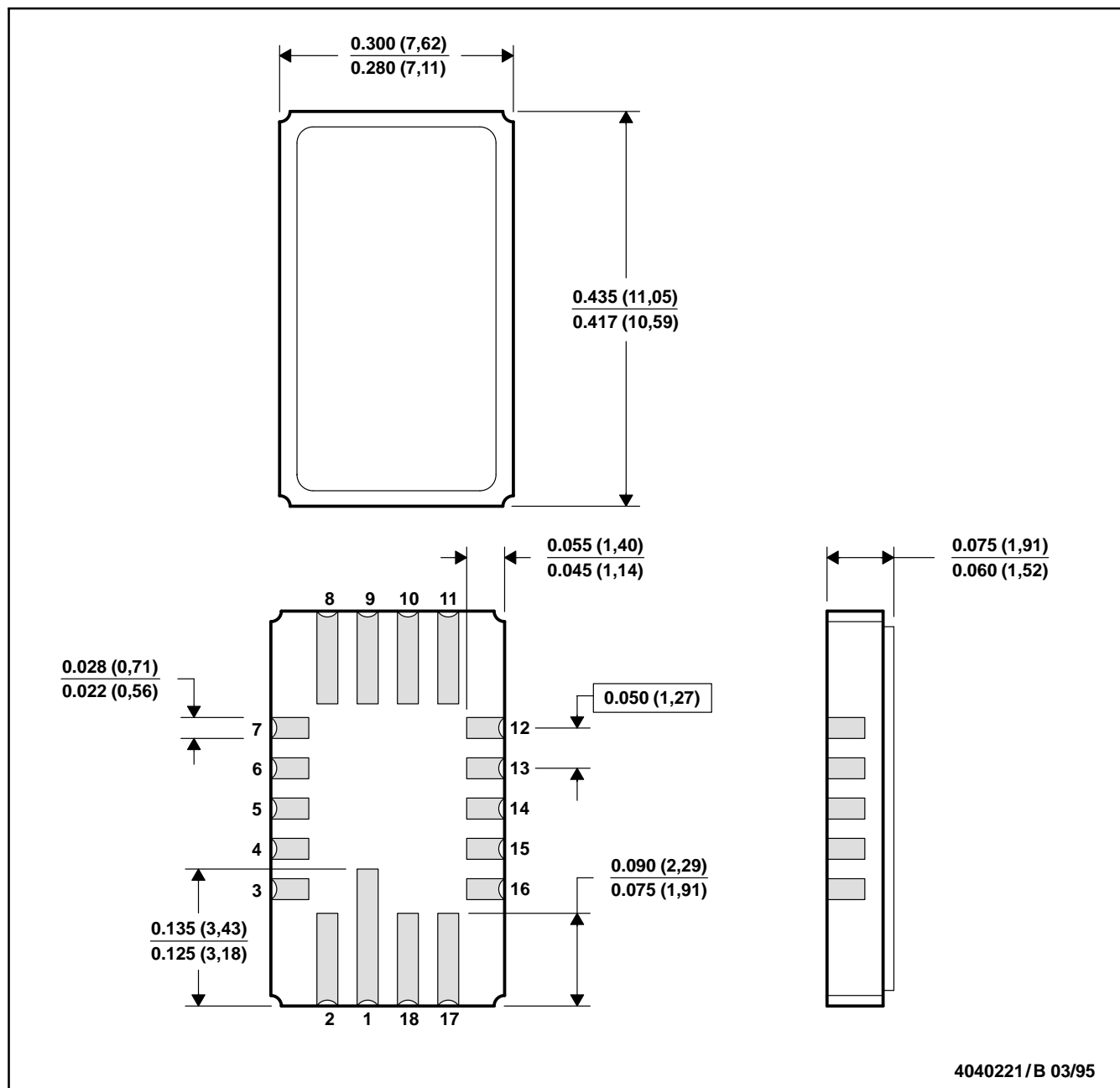


FG (R-CQCC-N18)

LEADLESS CERAMIC CHIP CARRIER



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within MIL STD 1835 CQCC4-N18 and JEDEC MO-041AC

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